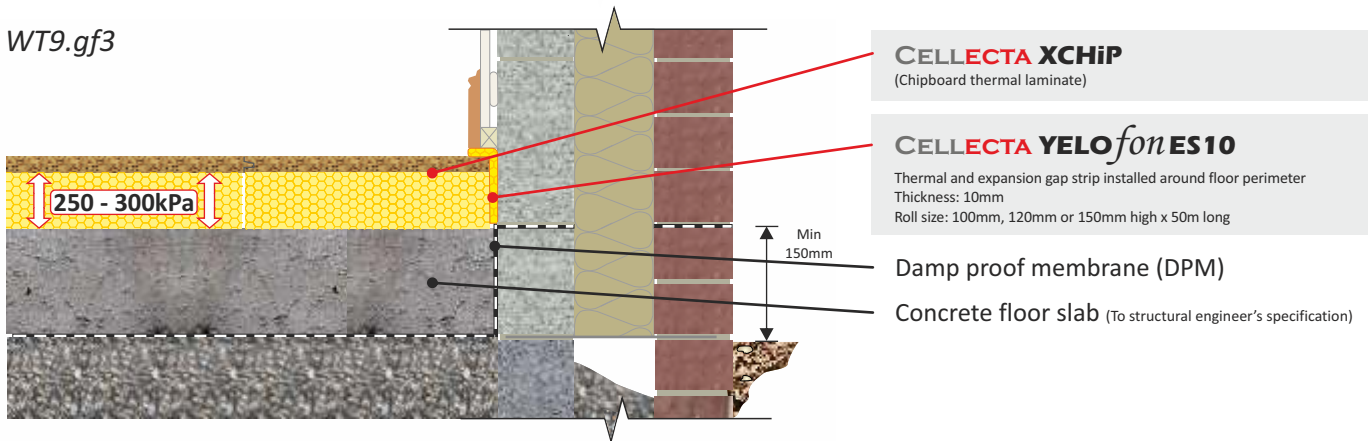


WT9.gf3



Product Information



CELLECTA's XCHIP combines the benefits of HEXATHERM high performance thermal insulation with an 18mm P5 moisture resistant, tongue and groove chipboard to produce a high compressive strength, interlocking floor board.

Key Benefits

- High compressive strength 250/300kPa
- Excellent life-long thermal performance
- Interlocking, moisture resistant chipboard facing
- Very low water absorption insulation
- Quick and easy to install

Physical Properties

		XCHIP
Thermal Conductivity EN 12667	W/mK	0.033 ≤80mm 0.034 >81mm
Strength at 10% compression EN 826	kPa	250 ≤30mm 300 >40mm
Strength at 2% compression EN 1606	kPa	80 ≤30mm 125 >40mm
Long term water absorption by immersion EN 12087	%	>0.7
Board size	mm	600 x 2400
Thickness' available - including 18mm P5 moisture resistant T & G chipboard (other sizes manufactured to order)	mm	38, 43, 48 58, 68, 93, 98, 118, 138, 158, 178
Edge profile	-	T&G

Typical Thickness of Insulation Required

P/A ratio	HEXATHERM XCHIP (mm)							
0.7	90	110	120	140	160	190	230	280
0.6	80	110	120	140	160	190	230	280
0.5	75	100	110	130	150	180	220	270
0.4	70	90	100	120	140	170	210	260
0.3	60	75	90	110	130	150	200	250
	0.25	0.22	0.20	0.18	0.16	0.14	0.12	0.10

U-value (W/m²K)
Calculated in accordance with ISO 13370

Third Party Accreditation and Approvals



BE 009119-1



Environmental Credentials

